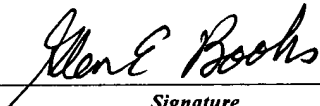
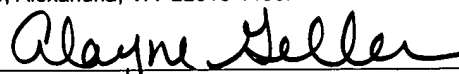


Image

1753

TRANSMITTAL OF FORMAL DRAWINGS				Docket No. Khaselev 2-2-28	
In Re Application Of: <b>O. KHASELEV et al.</b>					
Serial No. 10/050,014	Filing Date 01/17/2002	Confirmation No. 5508	Examiner WONG, EDNA	Art Unit 1753	
Invention: <b>ELECTROPLATING SOLUTION FOR HIGH SPEED PLATING OF TIN-BISMUTH SOLDER</b>					
<p>Address to: Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450</p> <p>Transmitted herewith are:</p> <p>ONE (1) sheets of formal drawing(s) for this application.</p> <p><input checked="" type="checkbox"/> Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).</p>					
<p> Signature</p> <p><b>GLEN E. BOOKS</b> REG. NO. 24,950</p> <p><b>LOWENSTEIN SANDLER PC</b> 65 LIVINGSTON AVENUE ROSELAND, NEW JERSEY 07068 973-597-6162</p>			<p>Dated: <u>01/07/2004</u></p> <p>I certify that this document and attached formal drawings are being deposited on <u>01/07/2004</u> with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.</p> <p> Signature of Person Mailing Correspondence</p> <p><b>ALAYNE GELLER</b> Typed or Printed Name of Person Mailing Correspondence</p>		